



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	21-07-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32WBA55CGU6 STM32WBA55CGU6TR	75MI*492XXB	A	998Z	21-07-2023
Amount	UoM	Unit type	ST ECOPACK Grade	
101.60	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	75M1*492XXB				5999999.0	999999.6				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.913	mg	supplier	die	Silicon (Si)	7440-21-3		2.628	mg	902163	25866				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.032	mg	10985	315				
				supplier	metallization	Copper (Cu)	7440-50-8		0.094	mg	32269	925				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.016	mg	5493	157				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1373	39				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	343	10				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	7552	217				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.116	mg	39821	1142				
				Glue epoxy (EN4900GC)	M-011 Other inorganic materials	0.424	mg	Supplier	Organic Compounds	Acrylic resin	Trade Secret		0.030	mg	70000	292
								Supplier	Organic Compounds	Polybutadiene derivative	Trade Secret		0.008	mg	20000	83
Supplier	Organic Compounds	Butadiene copolymer	Trade Secret						0.006	mg	15000	63				
Supplier	Organic Compounds	Acrylate	Trade Secret						0.023	mg	54000	225				
Supplier	Organic Compounds	Epoxy resin	Trade Secret						0.013	mg	30000	125				
Supplier	Organic Compounds	Peroxide	Trade Secret						0.003	mg	8000	33				
Supplier	Organic Compounds	Additive	Trade Secret						0.008	mg	18000	75				
Supplier	Metals	Silver (Ag)	7440-22-4						0.333	mg	785000	3276				
Mold Compound (EME-G770)	M-011 Other inorganic materials	36.040	mg					Supplier	Organic Compounds	Epoxy Resin A	Trade Secret		0.757	mg	21000	7449
								Supplier	Organic Compounds	Epoxy Resin B	Trade Secret		0.757	mg	21000	7449
				Supplier	Organic Compounds	Phenol Resin A	Trade Secret		0.757	mg	21000	7449				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		28.128	mg	780450	276847				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		4.156	mg	115320	40907				
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.225	mg	6230	2210				
				Supplier	Metallic compounds	Metal Hydroxide	Trade Secret		0.505	mg	14000	4966				
				Supplier	Organic Compounds	Phenol Resin B	Trade Secret		0.757	mg	21000	7449				
Bonding Wire (Au)	Bonding Wire	1.044	mg	Supplier	Metals	Gold (Au)	7440-57-5		1.044	mg	1000000	10275				
Plating (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	10614				
Leadframe (C7025 + Ag)	Copper & its alloys	60.100	mg	Supplier	Metals	Copper (Cu)	7440-50-8		55.120	mg	917140	542524				
				Supplier	Metals	Nickel (Ni)	7440-02-0		1.352	mg	22500	13310				
				Supplier	Metals	Silicon (Si)	7440-21-3		0.156	mg	2600	1538				
				Supplier	Metals	Magnesium (Mg)	7439-95-4		0.069	mg	1150	680				
				Supplier	Metals	Silver (Ag)	7440-22-4		3.402	mg	56610	33487				